

Low Capacitance Quad Line ESD Protection Diode Array SM05 SOT23-3

General Description

The SM05 of transient voltage suppressors (TVS) are designed to protect components which are connected to data and transmission lines from voltage surges caused by electrostatic discharge (ESD). TVS diodes are characterized by their high surge capability, low operating and clamping voltages, and fast response time. This makes them ideal for use as board level protection of sensitive semiconductor components. The dual-junction common-anode design allows the user to protect one bidirectional data line or two unidirectional lines. The low profile SOT23 package allows flexibility in the design of “crowded” circuit boards. The SM05 will meet the surge requirements of IEC 61000-4-2 (Formerly IEC801-2), Level 4, “Human Body Model” for air and contact discharge.

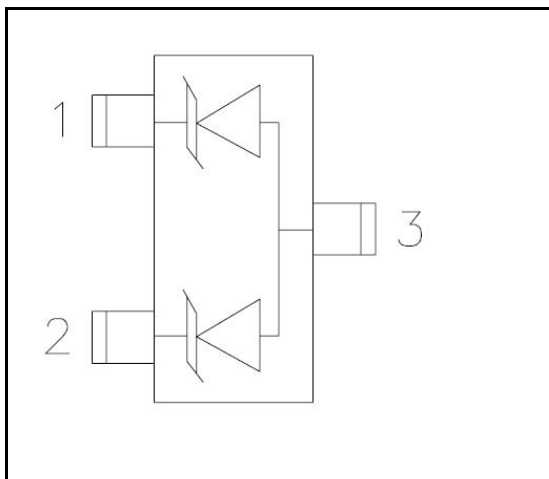
Applications

Cellular Handsets and Accessories
 Portable Electronics
 Industrial Controls
 Set-Top Box
 Servers, Notebook, and Desktop PC

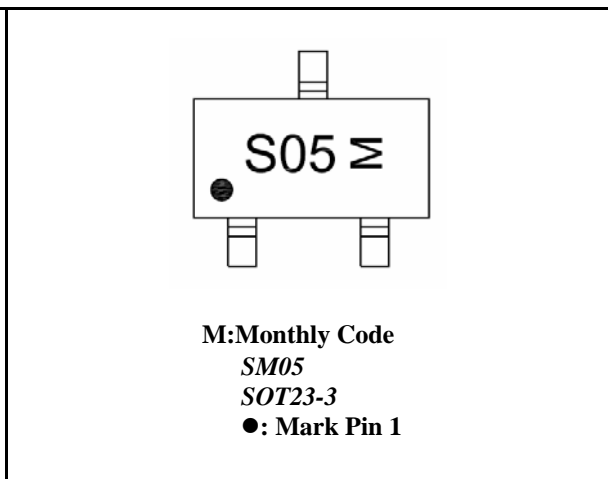
Features

Transient protection for data & power lines to
 IEC 61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$
 (contact) Protects one bidirectional line or two
 unidirectional lines
 Working Voltages: 5V
 Low clamping voltage
 Solid-state silicon avalanche technology

Pin Configurations



Top View



Ordering Information

Part Number	Working Voltage	Packaging Type	Channel	Marking Code	Shipping Qty
SM05	5.0V	SOT23-3	2	S05	3000/7 Inch Reel

Absolute Maximum Ratings

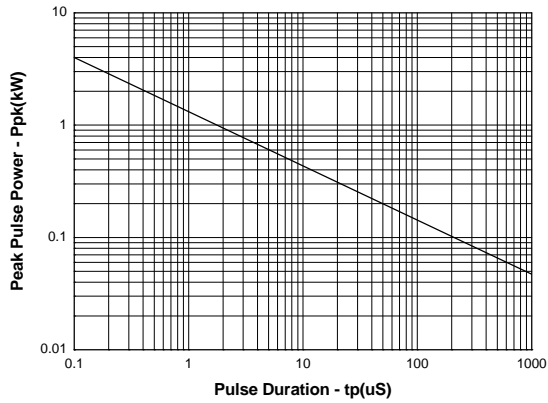
RATING	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PK}	300	Watts
Thermal Resistance, Junction to Ambient	θ_{JA}	325	$^{\circ}C/W$
Lead Soldering Temperature	T_L	260(10 sec.)	$^{\circ}C$
Operating Temperature	T_J	-55 to +125	$^{\circ}C$
Storage Temperature	T_{STG}	-55 to +125	$^{\circ}C$

Electrical Characteristics

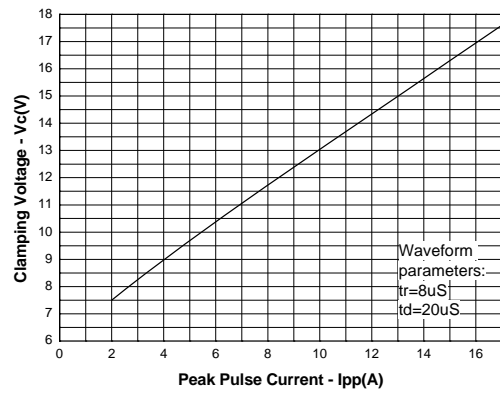
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	6	6.8	7.2	V
Reverse Leakage Current	I_R	$V_{RWM} = 5V, T = 25^{\circ}C$			0.1	μA
Clamping Voltage	V_C	$I_{PP} = 5A, t_p = 8/20 \mu S$			9.8	V
		$I_{PP} = 17A, t_p = 8/20 \mu S$			17.6	
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$			17	A
Junction Capacitance	C_J	Pin 1 to 2 $V_R = 0V,$ $f = 1MHz$		25		pF
Junction Capacitance	C_J	Pin 1 to 3 and Pin 2 to 3 $V_R = 0V, f = 1MHz$		50		pF
Reverse dynamic resistance	$R_{dyn,rev}$	$I_{PP} > 2A$		0.55		Ω
Forward dynamic resistance	$R_{dyn,fwd}$			0.35		

Typical Operating Characteristics

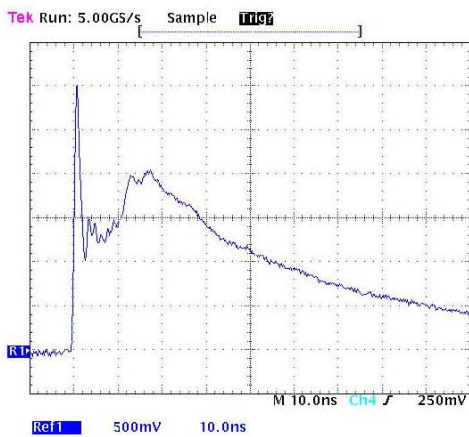
Non-Repetitive Peak Pulse Power vs. Pulse Time



Clamping Voltage vs. Peak Pulse Current



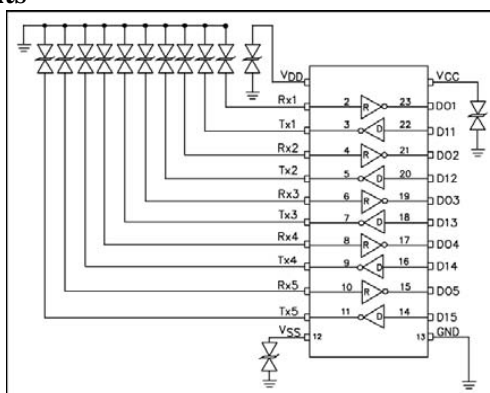
ESD Pulse Waveform (Per IEC 61000-4-2)



IEC 61000-4-2 Discharge Parameters

Level	First Peak Current (A)	Peak Current at 30 ns (A)	Peak Current at 60 ns (A)	Test Voltage (Contact Discharge) (kV)	Test Voltage (Air Discharge) (kV)
1	7.5	4	8	2	2
2	15	8	4	4	4
3	22.5	12	6	6	8
4	30	16	8	8	15

Typical Operating Circuits



Detailed Description

Device Connection Options

The SM05 is designed to protect one bidirectional or two unidirectional data or I/O lines operating at 5 volts. Connection options are as follows: Bidirectional: Pin 1 is connected to the data line and pin 2 is connected to ground (Since the device is symmetrical, these connections may be reversed). The ground connection should be made directly to a ground plane. The path length should be kept as short as possible to minimize parasitic inductance. Pin 3 is not connected. Unidirectional: Data lines are connected to pin 1 and pin 2. Pin 3 is connected to ground. For best results, this pin should be connected directly to a ground plane on the board. The path length should be kept as short as possible to minimize parasitic inductance.

Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of fast rise-time transients such as ESD. The following guidelines are recommended (Refer to application note SI99-01 for more detailed information): Place the TVS near the input terminals or connectors to restrict transient coupling. Minimize the path length between the TVS and the protected line. Minimize all conductive loops including power and ground loops. The ESD transient return path to ground should be kept as short as possible. Never run critical signals near board edges. Use ground planes whenever possible.

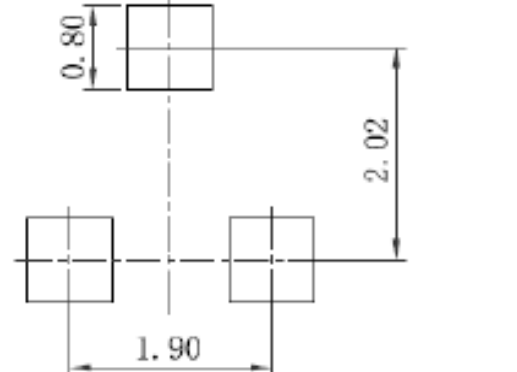
Matte Tin Lead Finish

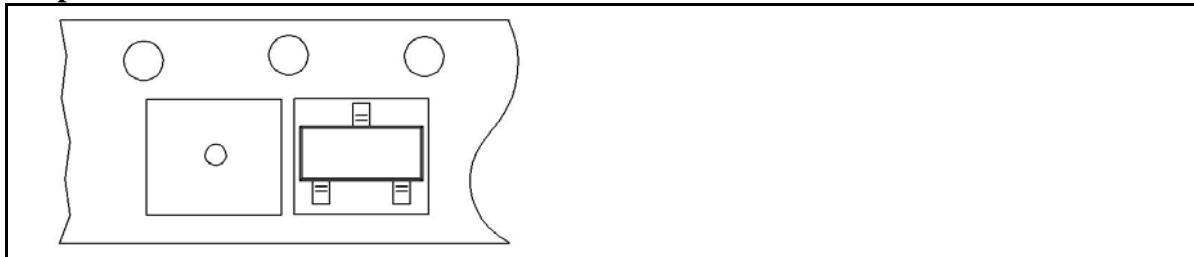
Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

Package Information
SM05: SOT23-3
Outline Drawing

DIMENSIONS				
Symbol	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.900	1.200	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.100	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.180	0.003	0.007
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.050	0.071	0.080
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Land Pattern

	<p>NOTES:</p> <ol style="list-style-type: none"> 1. Compound dimension: 2.90×1.30; 2. Unit: mm; 3. General tolerance±0.05mm unless otherwise specified; 4. The layout is just for reference.
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Tape and Reel Orientation


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Union Semiconductor, Inc

Add: 2F, No. 3, Lane647 Songtao Road, Shanghai 201203

Tel: 021-51093966

Fax: 021-51026018

Website: www.union-ic.com